

STF15N65M5, STF15N65M5, STP15N65M5

N-channel 650 V, 0.308 Ω typ., 11 A MDmesh™ V Power MOSFET in TO-220FP, I²PAKFP and TO-220 packages

Datasheet — production data

Features

Order codes	V _{DS} @ T _{Jmax}	R _{DS(on)} max	I _D
STF15N65M5			
STFI15N65M5	710 V	< 0.34 Ω	11 A
STP15N65M5			

- Worldwide best R_{DS(on)} * area
- Higher V_{DSS} rating and high dv/dt capability
- Excellent switching performance
- 100% avalanche tested

Applications

Switching applications

Description

These devices are N-channel MDmesh™ V Power MOSFETs based on an innovative proprietary vertical process technology, which is combined with STMicroelectronics' well-known PowerMESH™ horizontal layout structure. The resulting product has extremely low onresistance, which is unmatched among siliconbased Power MOSFETs, making it especially suitable for applications which require superior power density and outstanding efficiency.

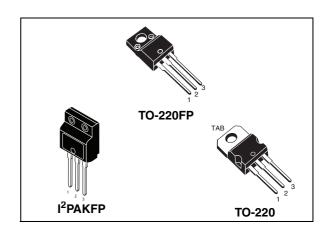


Figure 1. Internal schematic diagram

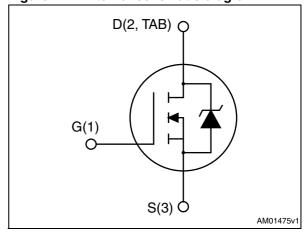


Table 1. Device summary

Order codes	Marking	Package	Packaging
STF15N65M5		TO-220FP	
STFI15N65M5	15N65M5	I ² PAKFP	Tube
STP15N65M5		TO-220	

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1 Electrical ratings

Table 2. Absolute maximum ratings

		Va		
Symbol	Parameter	TO-220	TO-220FP I ² PAKFP	Unit
V_{GS}	Gate-source voltage	±	25	٧
I _D	Drain current (continuous) at T _C = 25 °C	11	11 ⁽¹⁾	Α
I _D	Drain current (continuous) at T _C = 100 °C	6.9	6.9 ⁽¹⁾	Α
I _{DM} ⁽¹⁾	Drain current (pulsed)	44	44 ⁽¹⁾	Α
P _{TOT}	Total dissipation at T _C = 25 °C	85	25	W
dv/dt (2)	Peak diode recovery voltage slope	15		V/ns
V _{ISO}	Insulation withstand voltage (RMS) from all three leads to external heat sink (t = 1 s; Tc = 25 °C)	2500		V
T _{stg}	Storage temperature	- 55 to 150		°C
T _j	Max. operating junction temperature	15	50	°C

^{1.} Limited by maximum junction temperature.

Table 3. Thermal data

		Val		
Symbol	Parameter	TO-220FP I ² PAKFP	TO-220	Unit
R _{thj-case}	Thermal resistance junction-case max	5	1.47	°C/W
R _{thj-amb}	Thermal resistance junction-ambient max	62.5		°C/W

Table 4. Avalanche characteristics

Symbol	Parameter	Value	Unit
I _{AR}	Avalanche current, repetetive or not repetetive (pulse width limited by $T_{\rm jmax}$)	2.5	Α
E _{AS}	Single pulse avalanche energy (starting t_j = 25°C, I_D = I_{AR} ; V_{DD} =50 V)	160	mJ

^{2.} $I_{SD} \leq$ 11 A, di/dt \leq 400 A/ μ s; $V_{DD} =$ 400 V, $V_{DS(peak)} < V_{(BR)DSS}$

2 Electrical characteristics

(T_C = 25 °C unless otherwise specified)

Table 5. On /off states

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-source breakdown voltage	I _D = 1 mA, V _{GS} = 0	650			٧
I _{DSS}	Zero gate voltage drain current (V _{GS} = 0)	V _{DS} = 650 V V _{DS} = 650 V, T _C =125 °C			1 100	μ Α μ Α
I _{GSS}	Gate-body leakage current (V _{DS} = 0)	$V_{GS} = \pm 25 \text{ V}$			± 100	nA
V _{GS(th)}	Gate threshold voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	3	4	5	٧
R _{DS(on)}	Static drain-source on- resistance	$V_{GS} = 10 \text{ V}, I_D = 5.5 \text{ A}$		0.308	0.34	Ω

Table 6. Dynamic

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
C _{iss} C _{oss} C _{rss}	Input capacitance Output capacitance Reverse transfer capacitance	V _{DS} = 100 V, f = 1 MHz, V _{GS} = 0	-	816 23 2.6	-	pF pF pF
C _{o(tr)} ⁽¹⁾	Equivalent capacitance time related	V _{DS} = 0 to 520 V, V _{GS} = 0	-	70	-	pF
C _{o(er)} ⁽²⁾	Equivalent capacitance energy related	V _{DS} = 0 to 320 V, V _{GS} = 0	-	21	-	pF
R_{G}	Intrinsic gate resistance	f = 1 MHz open drain	ı	5	ı	Ω
Q_g	Total gate charge	$V_{DD} = 520 \text{ V}, I_D = 5.5 \text{ A},$		22		nC
Q_{gs}	Gate-source charge	V _{GS} = 10 V	-	5.5	-	nC
Q_{gd}	Gate-drain charge	(see Figure 18)		11		nC

^{1.} Time related is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS}

^{2.} Energy related is defined as a constant equivalent capacitance giving the same stored energy as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS}

Table 7. Switching times

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t _{d(V)}	Voltage delay time	$V_{DD} = 400 \text{ V}, I_{D} = 7 \text{ A},$		30		ns
t _{r (V)}	Voltage rise time	$R_G = 4.7 \Omega$, $V_{GS} = 10 V$		8		ns
t _{f (i)}	Current fall time	(see <i>Figure 19</i> and	_	11	_	ns
t _{c(off)}	Crossing time	Figure 22)		12.5		ns

Table 8. Source drain diode

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
I _{SD}	Source-drain current Source-drain current (pulsed)		-		11 44	A A
V _{SD} (2)	Forward on voltage	I _{SD} = 11 A, V _{GS} = 0	-		1.5	V
t _{rr} Q _{rr} I _{RRM}	Reverse recovery time Reverse recovery charge Reverse recovery current	I _{SD} = 11 A, di/dt = 100 A/μs V _{DD} = 100 V (see <i>Figure 22</i>)	1	247 2.4 19.5		ns μC A
t _{rr} Q _{rr} I _{RRM}	Reverse recovery time Reverse recovery charge Reverse recovery current	$I_{SD} = 11 \text{ A, di/dt} = 100 \text{ A/µs}$ $V_{DD} = 100 \text{ V, T}_{j} = 150 \text{ °C}$ (see <i>Figure 22</i>)	-	312 3 19		ns μC A

^{1.} Pulse width limited by safe operating area.

^{2.} Pulsed: pulse duration = $300 \mu s$, duty cycle 1.5%

2.1 Electrical characteristics (curves)

Figure 2. Safe operating area for TO-220FP Figure 3. Thermal impedance for TO-220FP and I²PAKFP and I²PAKFP

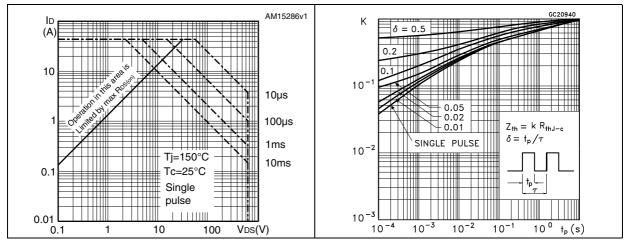


Figure 4. Safe operating area for TO-220 Figure 5. Thermal impedance for TO-220

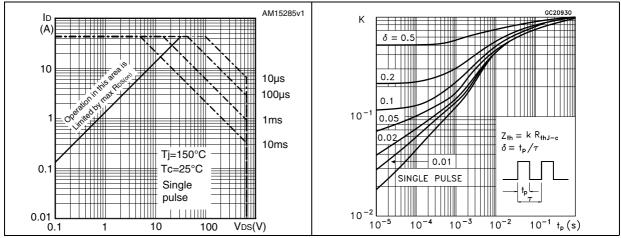
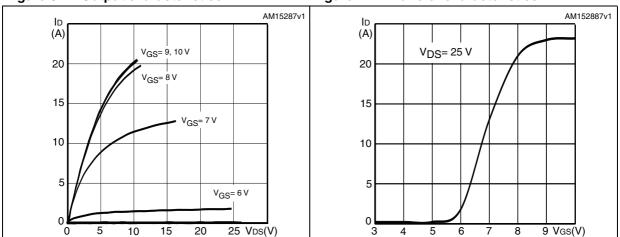


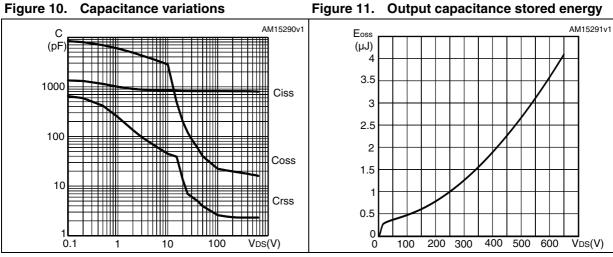
Figure 6. Output characteristics Figure 7. Transfer characteristics



AM15289v1 AM15293v1 Vgs RDS(on) VDS (V) (Ω) VDD=520V (V) 12 500 0.35 Vgs=10V ID=5.5A VDS 10 400 0.33 8 300 0.31 6 0.29 200 100 0.27 2 0.25 25 Qg(nC) 5 10 15 20 10 ID(A) 4 6 2 8

Figure 8. Gate charge vs gate-source voltage Figure 9. Static drain-source on-resistance

Figure 10. **Capacitance variations**



Normalized gate threshold voltage Figure 13. Figure 12. Normalized on-resistance vs vs temperature temperature

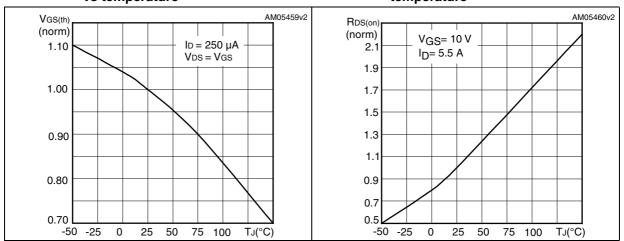
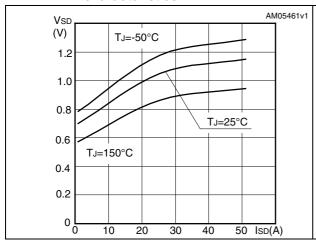


Figure 14. Source-drain diode forward characteristics

Figure 15. Normalized \mathbf{B}_{VDSS} vs temperature



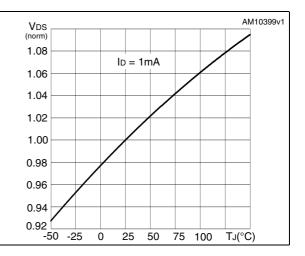
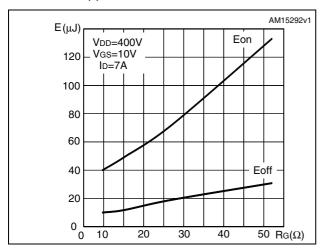


Figure 16. Switching losses vs gate resistance



1. Eon including reverse recovery of a SiC diode

3 Test circuits

Figure 17. Switching times test circuit for resistive load

Figure 18. Gate charge test circuit

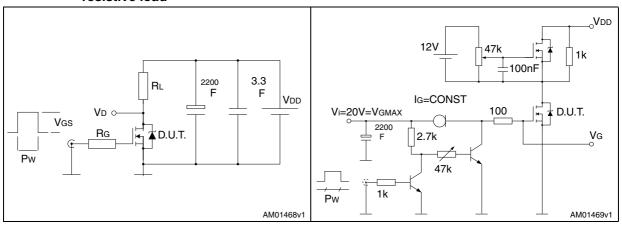


Figure 19. Test circuit for inductive load switching and diode recovery times

Figure 20. Unclamped inductive load test circuit

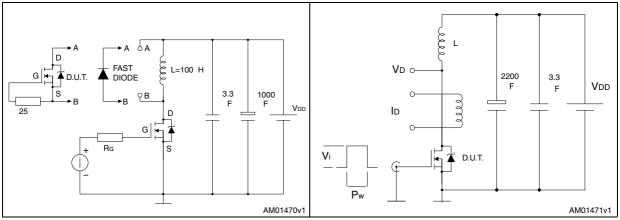
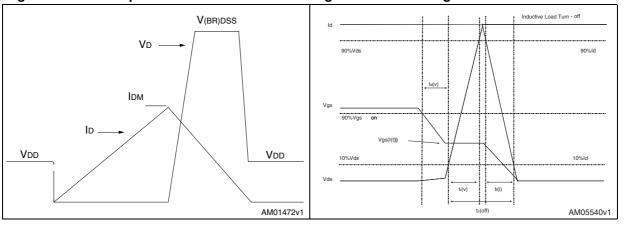


Figure 21. Unclamped inductive waveform

Figure 22. Switching time waveform



4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK[®] is an ST trademark.

Table 9. TO-220FP mechanical data

Di		mm			
Dim.	Min.	Тур.	Max.		
А	4.4		4.6		
В	2.5		2.7		
D	2.5		2.75		
Е	0.45		0.7		
F	0.75		1		
F1	1.15		1.70		
F2	1.15		1.70		
G	4.95		5.2		
G1	2.4		2.7		
Н	10		10.4		
L2		16			
L3	28.6		30.6		
L4	9.8		10.6		
L5	2.9		3.6		
L6	15.9		16.4		
L7	9		9.3		
Dia	3		3.2		

Figure 23. TO-220FP drawing

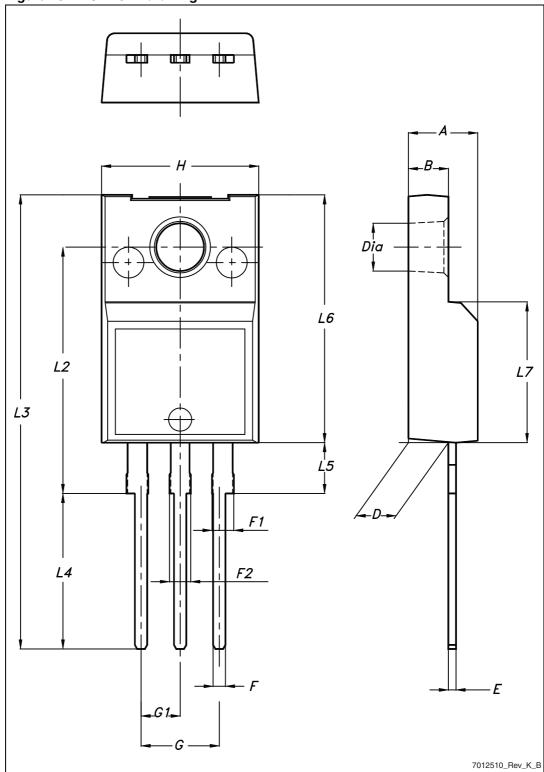


Table 10. I²PAKFP (TO-281) mechanical data

Dim.	mm		
Dim.	Min.	Тур.	Max.
Α	4.40		4.60
В	2.50		2.70
D	2.50		2.75
D1	0.65		0.85
E	0.45		0.70
F	0.75		1.00
F1			1.20
G	4.95	-	5.20
Н	10.00		10.40
L1	21.00		23.00
L2	13.20		14.10
L3	10.55		10.85
L4	2.70		3.20
L5	0.85		1.25
L6	7.30		7.50

Figure 24. I²PAKFP (TO-281) drawing

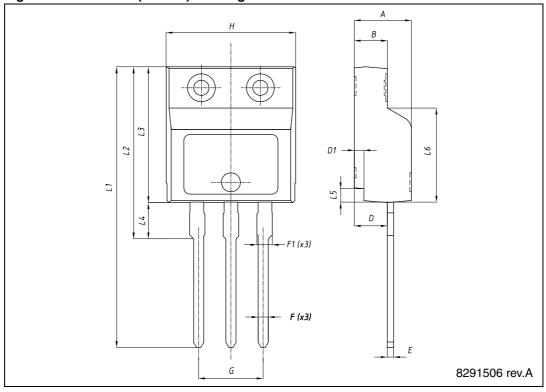
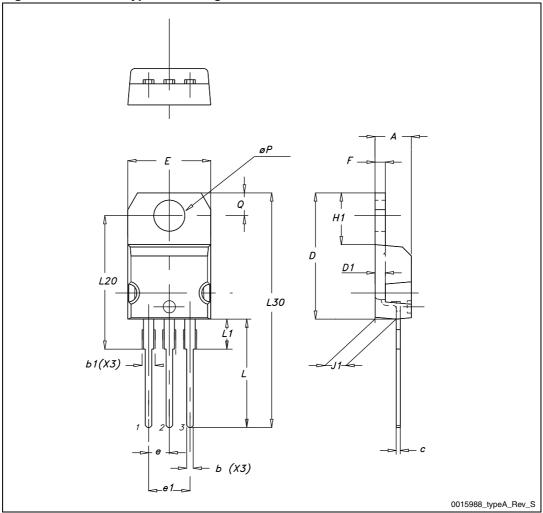


Table 11. TO-220 type A mechanical data

D:	mm			
Dim.	Min.	Тур.	Max.	
А	4.40		4.60	
b	0.61		0.88	
b1	1.14		1.70	
С	0.48		0.70	
D	15.25		15.75	
D1		1.27		
Е	10		10.40	
е	2.40		2.70	
e1	4.95		5.15	
F	1.23		1.32	
H1	6.20		6.60	
J1	2.40		2.72	
L	13		14	
L1	3.50		3.93	
L20		16.40		
L30		28.90		
ØP	3.75		3.85	
Q	2.65		2.95	

Figure 25. TO-220 type A drawing



5 Revision history

Table 12. Document revision history

Date	Revision	Changes	
05-Mar-2012	1	First release.	
09-Nov-2012	2	 The part number STB15N65M5 has been moved to a separate datasheet. Added Section 2.1: Electrical characteristics (curves). Minor text changes. 	

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